

## DUAL FREQUENCY VOLTAGE-CONTROLLED CRYSTAL OSCILLATOR (VCXO) 100 kHz TO 250 MHz

### Features

- Supports any frequency from 100 kHz to 250 MHz
- Two selectable output frequencies
- Low-jitter operation
- Short lead times: <2 weeks
- AT-cut fundamental mode crystal ensures high reliability/low aging
- High power supply noise rejection
- 1% control voltage linearity
- Available CMOS, LVPECL, LVDS, and HCSL outputs
- Optional 1:2 CMOS fanout buffer
- 3.3 and 2.5 V supply options
- Industry-standard 3.2 x 5.0 mm and 5 x 7 mm package/pinouts
- Pb-free/RoHS-compliant
- Selectable Kv (60, 90, 120, 150 ppm/V)

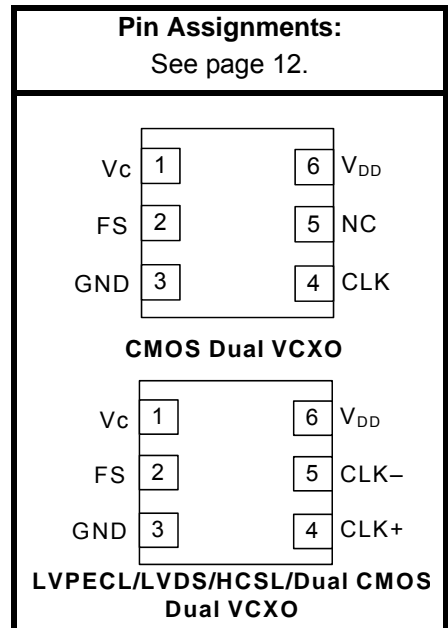
### Applications

- SONET/SDH/OTN
- PON
- Low Jitter PLLs
- xDSL
- Broadcast video
- Telecom
- Switches/routers
- FPGA/ASIC clock generation

### Description

The Si516 dual frequency VCXO utilizes Silicon Laboratories' advanced PLL technology to provide any frequency from 100 kHz to 250 MHz. Unlike a traditional VCXO where a different crystal is required for each output frequency, the Si516 uses one fixed crystal and Silicon Labs' proprietary synthesizer to generate any frequency across this range. This IC-based approach allows the crystal resonator to provide enhanced reliability, improved mechanical robustness, and excellent stability. In addition, this solution provides superior control voltage linearity and supply noise rejection, improving PLL stability and simplifying low jitter PLL design in noisy environments. The Si516 is factory-configurable for a wide variety of user specifications, including frequency, supply voltage, output format, tuning slope and stability. Specific configurations are factory-programmed at time of shipment, eliminating long lead times and non-recurring engineering charges associated with custom frequency oscillators.

### Functional Block Diagram





---

**TABLE OF CONTENTS**

---

<b><u>Section</u></b>	<b><u>Page</u></b>
<b>1. Electrical Specifications</b> .....	<b>4</b>
<b>2. Pin Descriptions</b> .....	<b>12</b>
2.1. Dual CMOS Buffer .....	13
<b>3. Ordering Information</b> .....	<b>14</b>
<b>4. Package Outline Diagram: 5 x 7 mm, 6-pin</b> .....	<b>15</b>
<b>5. PCB Land Pattern: 5 x 7 mm, 6-pin</b> .....	<b>17</b>
<b>6. Package Outline Diagram: 3.2 x 5.0 mm, 6-pin</b> .....	<b>18</b>
<b>7. PCB Land Pattern: 3.2 x 5.0 mm, 6-pin</b> .....	<b>19</b>
<b>8. Top Marking</b> .....	<b>20</b>
8.1. Si516 Top Marking .....	20
8.2. Top Marking Explanation .....	20
<b>Document Change List</b> .....	<b>21</b>
<b>Contact Information</b> .....	<b>22</b>

## 1. Electrical Specifications

**Table 1. Recommended Operating Conditions**

$V_{DD} = 2.5$  or  $3.3$  V  $\pm 10\%$ ,  $T_A = -40$  to  $+85$  °C

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Supply Voltage	$V_{DD}$	3.3 V option	2.97	3.3	3.63	V
		2.5 V option	2.25	2.5	2.75	V
Supply Current	$I_{DD}$	CMOS, 100 kHz, single-ended	—	24	29	mA
		LVDS (output enabled)	—	22	26	mA
		LVPECL (output enabled)	—	42	46	mA
		HCSL (output enabled)	—	44	47	mA
		Tristate (output disabled)	—	—	22	mA
FS "1" Setting	$V_{IH}$		$0.80 \times V_{DD}$	—	—	V
FS "0" Setting	$V_{IL}$		—	—	$0.20 \times V_{DD}$	V
FS Internal Pull-Up Resistor	$R_I$		—	45	—	k $\Omega$
Operating Temperature	$T_A$		-40	—	85	°C

**Table 2. Vc Control Voltage Input** $V_{DD} = 2.5$  or  $3.3$  V  $\pm 10\%$ ,  $T_A = -40$  to  $+85$  °C

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Control Voltage Range	$V_C$		$0.1 \times V_{DD}$	$V_{DD}/2$	$0.9 \times V_{DD}$	V
Control Voltage Tuning Slope (10 to 90% $V_{DD}$ )	Kv	Ordering option	60, 90, 120, 150			ppm/V
Kv Variation	Kv_var		—	—	$\pm 10$	%
Control Voltage Linearity	$L_{VC}$	BSL	-5	$\pm 1$	+5	%
Modulation Bandwidth	BW		—	10	—	kHz
Vc Input Impedance	$Z_{VC}$		—	100	—	k $\Omega$

**Table 3. Output Clock Frequency Characteristics** $V_{DD} = 2.5$  or  $3.3$  V  $\pm 10\%$ ,  $T_A = -40$  to  $+85$  °C

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Nominal Frequency	$F_O$	CMOS, Dual CMOS	0.1	—	212.5	MHz
	$F_O$	LVDS/LVPECL/HCSL	0.1	—	250	MHz
Temperature Stability	$S_T$	$T_A = -40$ to $+85$ °C	-20	—	+20	ppm
Aging	A	Frequency drift over 10-year life	—	—	$\pm 8.5$	ppm
Minimum Absolute Pull Range	APR	Ordering option	$\pm 30, \pm 50, \pm 80, \pm 100$			ppm
Startup Time	$T_{SU}$	Minimum $V_{DD}$ until output frequency ( $F_O$ ) within specification	—	—	10	ms
Disable Time	$T_D$	$F_O \geq 10$ MHz	—	—	5	$\mu$ s
		$F_O < 10$ MHz	—	—	40	$\mu$ s
Enable Time	$T_D$	$F_O \geq 10$ MHz	—	—	20	$\mu$ s
		$F_O < 10$ MHz	—	—	60	$\mu$ s
Settling Time after FS Change	$t_{FRQ}$		—	—	10	ms

**Table 4. Output Clock Levels and Symmetry**

$V_{DD} = 2.5$  or  $3.3$  V  $\pm 10\%$ ,  $T_A = -40$  to  $+85$  °C

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
CMOS Output Logic High	$V_{OH}$		$0.85 \times V_{DD}$	—	—	V
CMOS Output Logic Low	$V_{OL}$		—	—	$0.15 \times V_{DD}$	V
CMOS Output Logic High Drive	$I_{OH}$	3.3 V	-8	—	—	mA
		2.5 V	-6	—	—	mA
CMOS Output Logic Low Drive	$I_{OL}$	3.3 V	8	—	—	mA
		2.5 V	6	—	—	mA
CMOS Output Rise/Fall Time (20 to 80% $V_{DD}$ )	$T_R/T_F$	0.1 to 125 MHz, $C_L = 15$ pF	—	0.8	1.2	ns
		0.1 to 212.5 MHz, $C_L =$ no load	—	0.6	0.9	ns
LVPECL/HCSL Output Rise/Fall Time (20 to 80% $V_{DD}$ )	$T_R/T_F$		—	—	565	ps
LVDS Output Rise/Fall Time (20 to 80% $V_{DD}$ )	$T_R/T_F$		—	—	800	ps
LVPECL Output Common Mode	$V_{OC}$	$50 \Omega$ to $V_{DD} - 2$ V, single-ended	—	$V_{DD} - 1.4$ V	—	V
LVPECL Output Swing	$V_O$	$50 \Omega$ to $V_{DD} - 2$ V, single-ended	0.55	0.8	0.90	$V_{PPSE}$
LVDS Output Common Mode	$V_{OC}$	$100 \Omega$ line-line, $V_{DD} = 3.3/2.5$ V	1.13	1.23	1.33	V
LVDS Output Swing	$V_O$	Single-ended $100 \Omega$ differential termination	0.25	0.38	0.42	$V_{PPSE}$
HCSL Output Common Mode	$V_{OC}$	$50 \Omega$ to ground	0.35	0.38	0.42	V
HCSL Output Swing	$V_O$	Single-ended	0.58	0.73	0.85	$V_{PPSE}$
Duty Cycle	DC		48	50	52	%

**Table 5. Output Clock Jitter and Phase Noise (LVPECL)**V<sub>DD</sub> = 2.5 or 3.3 V ±10%, T<sub>A</sub> = -40 to +85 °C; Output Format = LVPECL

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Period Jitter (RMS)	J <sub>PRMS</sub>	10 k samples <sup>1</sup>	—	—	1.3	ps
Period Jitter (PK-PK)	J <sub>PPKPK</sub>	10 k samples <sup>1</sup> (brickwall)	—	—	11	ps
Phase Jitter (RMS)	φJ	12 kHz to 20 MHz <sup>2</sup> (brickwall)	—	0.9	1.3	ps
		1.875 MHz to 20 MHz <sup>2</sup> (brickwall)	—	0.25	0.5	ps
Phase Noise, 155.52 MHz	φN	100 Hz offset	—	-71	—	dBc/Hz
		1 kHz offset	—	-94	—	dBc/Hz
		10 kHz offset	—	-113	—	dBc/Hz
		100 kHz offset	—	-124	—	dBc/Hz
		1 MHz offset	—	-136	—	dBc/Hz
Additive RMS Jitter Due to External Power Supply Noise <sup>3</sup>	J <sub>PSRR</sub>	100 kHz sinusoidal noise	—	4.0	—	ps
		200 kHz sinusoidal noise	—	3.5	—	ps
		500 kHz sinusoidal noise	—	3.5	—	ps
		1 MHz sinusoidal noise	—	3.5	—	ps
Spurious Performance	SPR	F <sub>O</sub> = 156.25 MHz, Offset > 10 kHz	—	-75	—	dBc

**Notes:**

1. Applies to output frequencies: 74.17582, 74.25, 75, 77.76, 100, 106.25, 125, 148.35165, 148.5, 150, 155.52, 156.25, 212.5, 250 MHz.
2. Applies to output frequencies: 100, 106.25, 125, 148.35165, 148.5, 150, 155.52, 156.25, 212.5, 250 MHz.
3. 156.25 MHz. Increase in jitter on output clock due to spurs introduced by sinewave noise added to VDD (100 mV<sub>PP</sub>).

**Table 6. Output Clock Jitter and Phase Noise (LVDS)**

$V_{DD} = 1.8\text{ V} \pm 5\%$ , 2.5 or 3.3 V  $\pm 10\%$ ,  $T_A = -40$  to  $+85\text{ }^\circ\text{C}$ ; Output Format = LVDS

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Period Jitter (RMS)	JPRMS	10k samples <sup>1</sup>	—	—	2.1	ps
Period Jitter (Pk-Pk)	JPPKPK	10k samples <sup>1</sup>	—	—	18	ps
Phase Jitter (RMS)	$\phi J$	1.875 MHz to 20 MHz integration bandwidth <sup>2</sup> (brickwall)	—	0.25	0.55	ps
		12 kHz to 20 MHz integration bandwidth <sup>2</sup> (brickwall)	—	0.8	1.1	ps
Phase Noise, 156.25 MHz	$\phi N$	100 Hz	—	-72	—	dBc/Hz
		1 kHz	—	-93	—	dBc/Hz
		10 kHz	—	-114	—	dBc/Hz
		100 kHz	—	-123	—	dBc/Hz
		1 MHz	—	-136	—	dBc/Hz
Spurious	SPR	LVPECL output, 156.25 MHz, offset > 10 kHz	—	-75	—	dBc
<b>Notes:</b>						
1. Applies to output frequencies: 74.17582, 74.25, 75, 77.76, 100, 106.25, 125, 148.35165, 148.5, 150, 155.52, 156.25, 212.5, 250 MHz.						
2. Applies to output frequencies: 100, 106.25, 125, 148.35165, 148.5, 150, 155.52, 156.25, 212.5 and 250 MHz.						



**Table 7. Output Clock Jitter and Phase Noise (HCSL)**

$V_{DD} = 1.8\text{ V} \pm 5\%$ ,  $2.5\text{ or }3.3\text{ V} \pm 10\%$ ,  $T_A = -40\text{ to }+85\text{ }^\circ\text{C}$ ; Output Format = HCSL

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Period Jitter (RMS)	JPRMS	10k samples*	—	—	1.2	ps
Period Jitter (Pk-Pk)	JPPKPK	10k samples*	—	—	11	ps
Phase Jitter (RMS)	$\phi J$	1.875 MHz to 20 MHz integration bandwidth* (brickwall)	—	0.25	0.30	ps
		12 kHz to 20 MHz integration bandwidth* (brickwall)	—	0.8	1.0	ps
Phase Noise, 156.25 MHz	$\phi N$	100 Hz	—	-75	—	dBc/Hz
		1 kHz	—	-98	—	dBc/Hz
		10 kHz	—	-117	—	dBc/Hz
		100 kHz	—	-127	—	dBc/Hz
		1 MHz	—	-136	—	dBc/Hz
Spurious	SPR	LVPECL output, 156.25 MHz, offset > 10 kHz	—	-75	—	dBc

**\*Note:** Applies to an output frequency of 100 MHz.

**Table 8. Output Clock Jitter and Phase Noise (CMOS, Dual CMOS)**

$V_{DD} = 1.8\text{ V} \pm 5\%$ ,  $2.5\text{ or }3.3\text{ V} \pm 10\%$ ,  $T_A = -40\text{ to }+85\text{ }^\circ\text{C}$ ; Output Format = CMOS, Dual CMOS

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Phase Jitter (RMS)	$\phi_J$	1.875 MHz to 20 MHz integration bandwidth <sup>2</sup> (brickwall)	—	0.25	0.35	ps
		12 kHz to 20 MHz integration bandwidth <sup>2</sup> (brickwall)	—	0.8	1.1	ps
Phase Noise, 156.25 MHz	$\phi_N$	100 Hz	—	-71	—	dBc/Hz
		1 kHz	—	-93	—	dBc/Hz
		10 kHz	—	-113	—	dBc/Hz
		100 kHz	—	-123	—	dBc/Hz
		1 MHz	—	-136	—	dBc/Hz
Spurious	SPR	LVPECL output, 156.25 MHz, offset > 10 kHz	—	-75	—	dBc

**Notes:**

1. Applies to output frequencies: 74.17582, 74.25, 75, 77.76, 100, 106.25, 125, 148.35165, 148.5, 150, 155.52, 156.25, 212.5 MHz.
2. Applies to output frequencies: 100, 106.25, 125, 148.35165, 148.5, 150, 155.52, 156.25, 212.5 MHz.

**Table 9. Environmental Compliance and Package Information**

Parameter	Conditions/Test Method
Mechanical Shock	MIL-STD-883, Method 2002
Mechanical Vibration	MIL-STD-883, Method 2007
Solderability	MIL-STD-883, Method 2003
Gross and Fine Leak	MIL-STD-883, Method 1014
Resistance to Solder Heat	MIL-STD-883, Method 2036
Moisture Sensitivity Level	MSL 1
Contact Pads	Gold over Nickel

Table 10. Thermal Characteristics

Parameter	Symbol	Test Condition	Value	Unit
Thermal Resistance Junction to Ambient	$\theta_{JA}$	Still air	110	°C/W

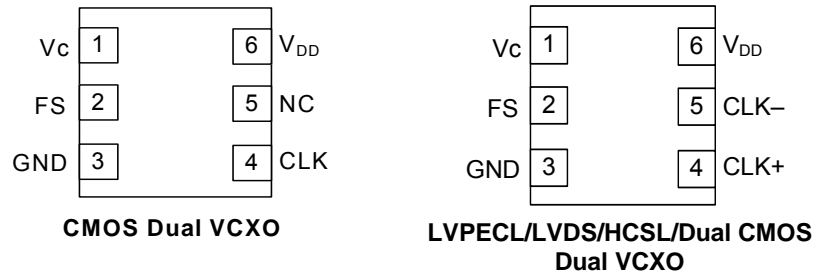
Table 11. Absolute Maximum Ratings<sup>1</sup>

Parameter	Symbol	Rating	Unit
Maximum Operating Temperature	$T_{AMAX}$	85	°C
Storage Temperature	$T_S$	-55 to +125	°C
Supply Voltage	$V_{DD}$	-0.5 to +3.8	V
Input Voltage (any input pin)	$V_I$	-0.5 to $V_{DD} + 0.3$	V
ESD Sensitivity (HBM, per JESD22-A114)	HBM	2	kV
Soldering Temperature (Pb-free profile) <sup>2</sup>	$T_{PEAK}$	260	°C
Soldering Temperature Time at $T_{PEAK}$ (Pb-free profile) <sup>2</sup>	$T_P$	20–40	sec

**Notes:**

1. Stresses beyond those listed in this table may cause permanent damage to the device. Functional operation or specification compliance is not implied at these conditions. Exposure to maximum rating conditions for extended periods may affect device reliability.
2. The device is compliant with JEDEC J-STD-020.

## 2. Pin Descriptions



**Table 12. Si516 Pin Descriptions (CMOS)**

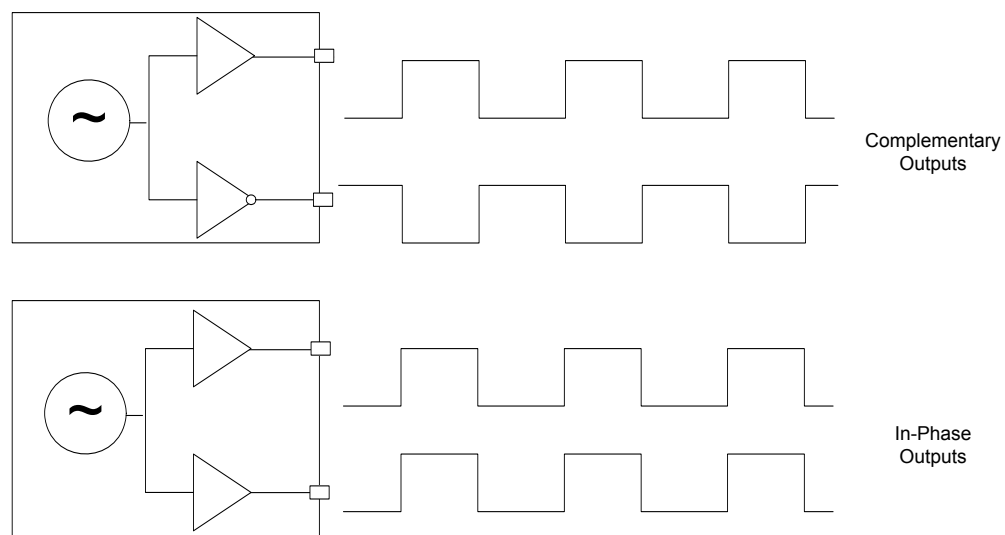
Pin	Name	CMOS Function
1	V <sub>C</sub>	Control Voltage Input.
2	FS	Frequency Select. 0 = First frequency selected. 1 = Second frequency selected.
3	GND	Electrical and Case Ground.
4	CLK	Clock Output.
5	NC	No connect. Make no external connection to this pin.
6	V <sub>DD</sub>	Power Supply Voltage.

**Table 13. Si516 Pin Descriptions (LVPECL/LVDS/HCSL/Dual CMOS)**

Pin	Name	LVPECL/LVDS/HCSL/Dual CMOS Function
1	V <sub>C</sub>	Control Voltage Input.
2	FS	Frequency Select. 0 = First frequency selected. 1 = Second frequency selected.
3	GND	Electrical and Case Ground.
4	CLK+	Clock Output.
5	CLK-	Complementary Clock Output.
6	V <sub>DD</sub>	Power Supply Voltage.

## 2.1. Dual CMOS Buffer

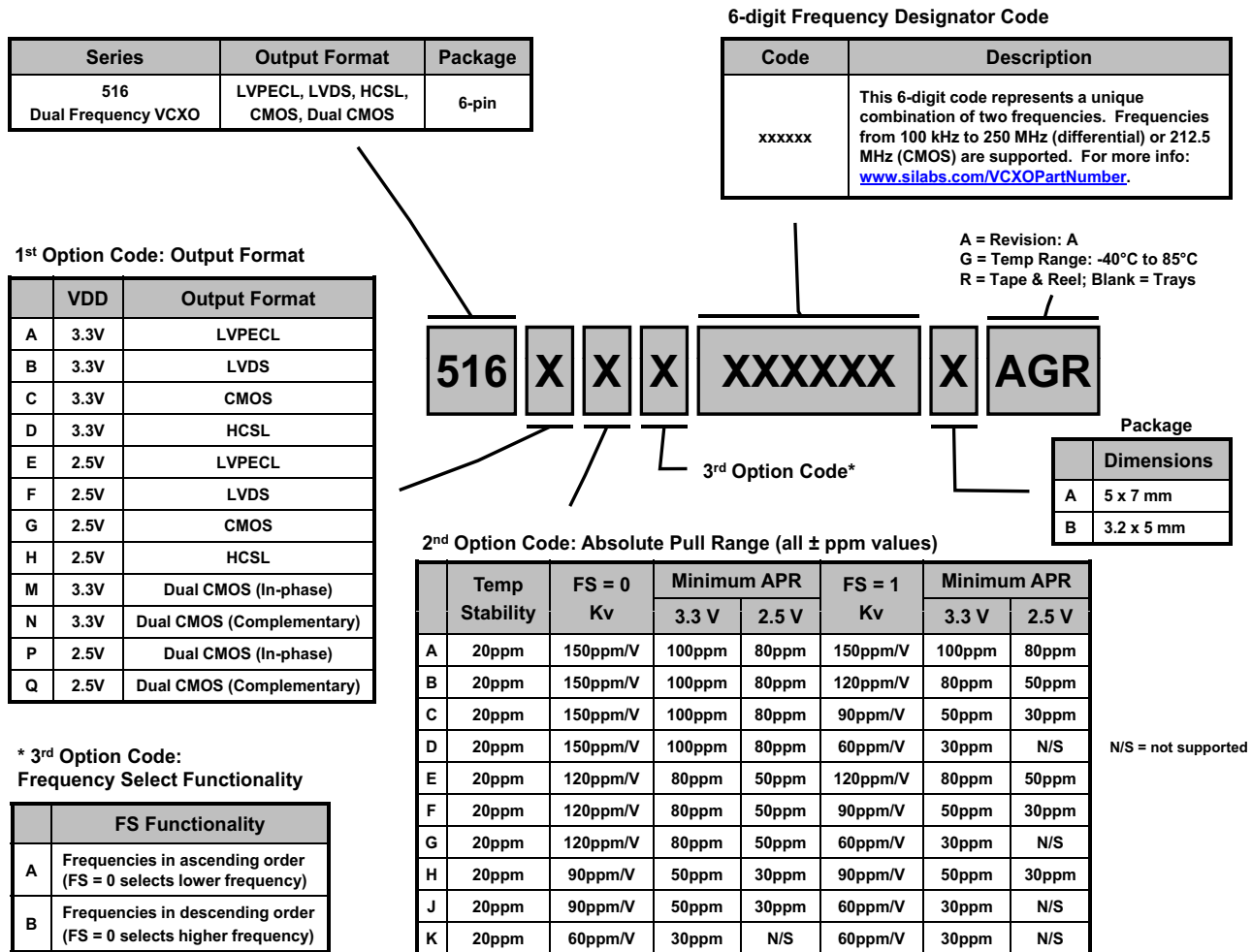
Dual CMOS output format ordering options support either complementary or in-phase output signals. This feature enables replacement of multiple VCXOs with a single Si516 device.



**Figure 1. Integrated 1:2 CMOS Buffer Supports Complementary or In-Phase Output**

## 3. Ordering Information

The Si516 supports a variety of options including frequency, minimum absolute pull range (APR), tuning slope, output format, and  $V_{DD}$ . Specific device configurations are programmed into the Si516 at time of shipment. Configurations are specified using the Part Number Configuration chart shown below. Silicon Labs provides a web browser-based part number configuration utility to simplify this process. Refer to [www.silabs.com/VCXOPartNumber](http://www.silabs.com/VCXOPartNumber) to access this tool and for further ordering instructions. The Si516 VCXO series is supplied in industry-standard, RoHS compliant, lead-free, 3.2 x 5.0 mm and 5 x 7 mm packages. Tape and reel packaging is an ordering option.



**Figure 2. Part Number Convention**

Example ordering part number: 516AAB000213AAG.

The series prefix, 516, indicates the device is a dual frequency VCXO.

The 1st option code A specifies the output format is LVPECL and powered from a 3.3 V supply. The Absolute Pull Range code A indicates a temperature stability of  $\pm 20$  ppm with a tuning slope of  $\pm 150$  ppm/V. The 3rd option code B specifies the frequencies are listed in descending order and FS = 0 selects the higher frequency.

The frequency code is 000213. Per this convention, and as indicated by the part number lookup utility at [www.silabs.com/VCXOPartNumber](http://www.silabs.com/VCXOPartNumber), the two output frequencies are 156.25 MHz and 125 MHz. The package code A refers to the 5 x 7 mm footprint with six pins. The last A refers to the product revision, G indicates the temperature range ( $-40$  to  $+85$  °C), and R specifies the device ships in tape and reel format.

#### 4. Package Outline Diagram: 5 x 7 mm, 6-pin

Figure 3 illustrates the package details for the Si516. Table 14 lists the values for the dimensions shown in the illustration.

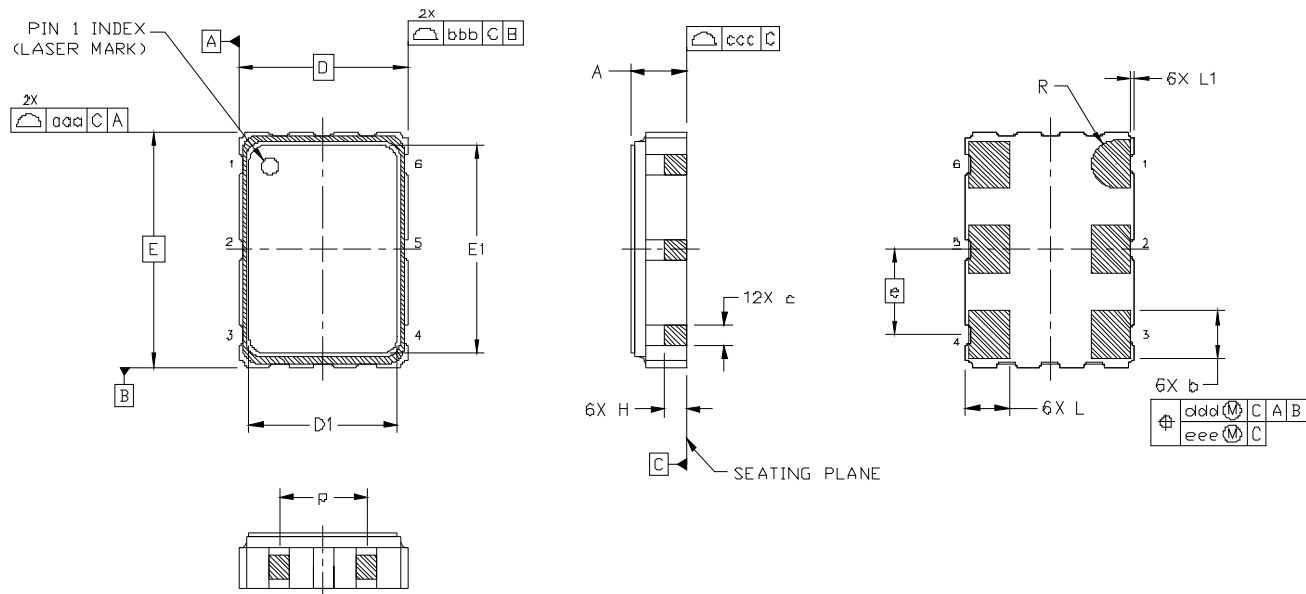


Figure 3. Si516 Outline Diagram

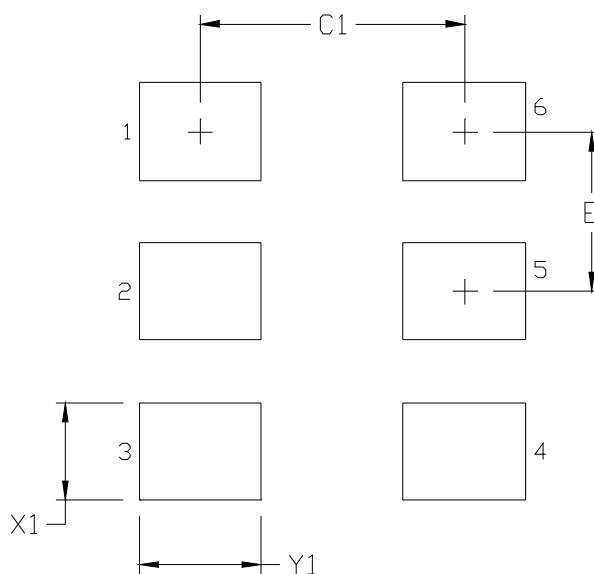
Table 14. Package Diagram Dimensions (mm)

Dimension	Min	Nom	Max
A	1.50	1.65	1.80
b	1.30	1.40	1.50
c	0.50	0.60	0.70
D	5.00 BSC		
D1	4.30	4.40	4.50
e	2.54 BSC		
E	7.00 BSC		
E1	6.10	6.20	6.30
H	0.55	0.65	0.75
L	1.17	1.27	1.37
L1	0.05	0.10	0.15
p	1.80	—	2.60
R	0.70 REF		
aaa	0.15		
bbb	0.15		
ccc	0.10		
ddd	0.10		
eee	0.05		
<b>Notes:</b>			
1. All dimensions shown are in millimeters (mm) unless otherwise noted.			
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.			



## 5. PCB Land Pattern: 5 x 7 mm, 6-pin

Figure 4 illustrates the 5 x 7 mm PCB land pattern for the Si516. Table 15 lists the values for the dimensions shown in the illustration.



**Figure 4. Si516 PCB Land Pattern**

**Table 15. PCB Land Pattern Dimensions (mm)**

Dimension	(mm)
C1	4.20
E	2.54
X1	1.55
Y1	1.95

**Notes:**

**General**

- All dimensions shown are in millimeters (mm) unless otherwise noted.
- Dimensioning and Tolerancing is per the ANSI Y14.5M-1994 specification.
- This Land Pattern Design is based on the IPC-7351 guidelines.
- All dimensions shown are at Maximum Material Condition (MMC). Least Material Condition (LMC) is calculated based on a Fabrication Allowance of 0.05 mm.

**Solder Mask Design**

- All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60  $\mu\text{m}$  minimum, all the way around the pad.

**Stencil Design**

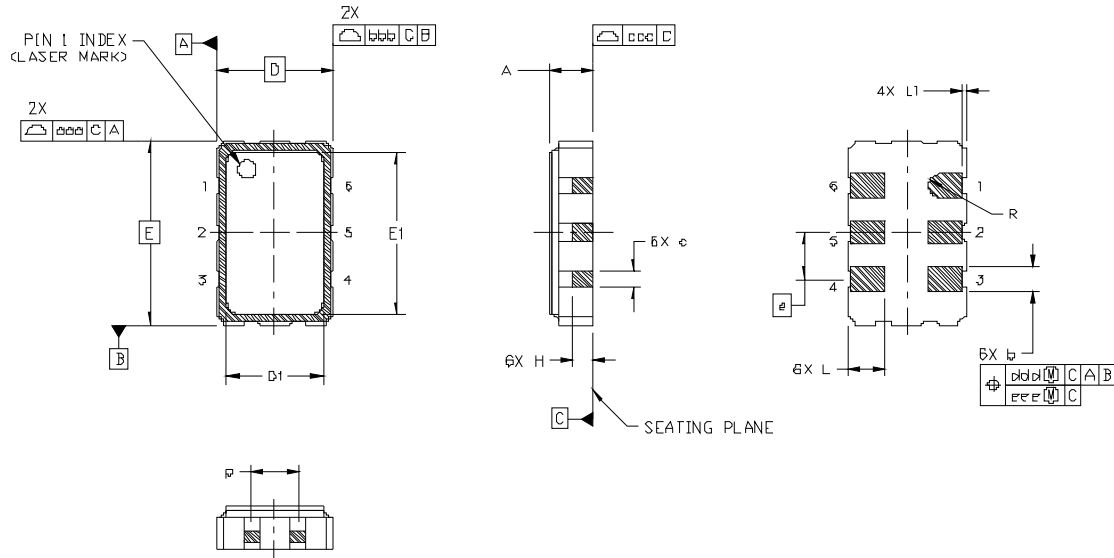
- A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
- The stencil thickness should be 0.125 mm (5 mils).
- The ratio of stencil aperture to land pad size should be 1:1.

**Card Assembly**

- A No-Clean, Type-3 solder paste is recommended.
- The recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

## 6. Package Outline Diagram: 3.2 x 5.0 mm, 6-pin

Figure 5 illustrates the package details for the 3.2 x 5 mm Si510/511. Table 16 lists the values for the dimensions shown in the illustration.



**Figure 5. Si510/511 Outline Diagram**

**Table 16. Package Diagram Dimensions (mm)**

Dimension	Min	Nom	Max
A	1.06	1.17	1.28
b	0.54	0.64	0.74
c	0.35	0.45	0.55
D	3.20 BSC		
D1	2.55	2.60	2.65
e	1.27 BSC		
E	5.00 BSC		
E1	4.35	4.40	4.45
H	0.45	0.55	0.65
L	0.90	1.00	1.10
L1	0.05	0.10	0.15
p	1.17	1.27	1.37
R	0.32 REF		
aaa	0.15		
bbb	0.15		
ccc	0.10		
ddd	0.10		
eee	0.05		
<b>Notes:</b>			
1. All dimensions shown are in millimeters (mm) unless otherwise noted.			
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.			

## 7. PCB Land Pattern: 3.2 x 5.0 mm, 6-pin

Figure 6 illustrates the recommended 3.2 x 5.0 mm PCB land pattern for the Si516. Table 17 lists the values for the dimensions shown in the illustration.

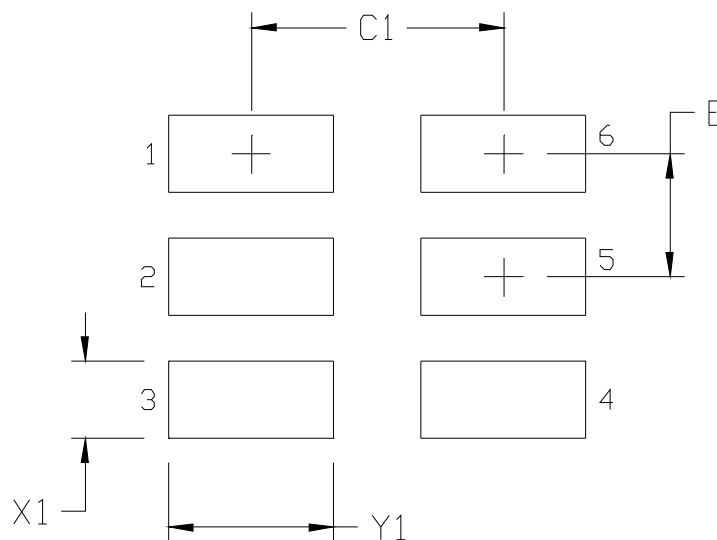


Figure 6. Si516 PCB Land Pattern

Table 17. PCB Land Pattern Dimensions (mm)

Dimension	(mm)
C1	2.60
E	1.27
X1	0.80
Y1	1.70

**Notes:**

**General**

- All dimensions shown are in millimeters (mm) unless otherwise noted.
- Dimensioning and Tolerancing is per the ANSI Y14.5M-1994 specification.
- This Land Pattern Design is based on the IPC-7351 guidelines.
- All dimensions shown are at Maximum Material Condition (MMC). Least Material Condition (LMC) is calculated based on a Fabrication Allowance of 0.05 mm.

**Solder Mask Design**

- All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60  $\mu\text{m}$  minimum, all the way around the pad.

**Stencil Design**

- A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
- The stencil thickness should be 0.125 mm (5 mils).
- The ratio of stencil aperture to land pad size should be 1:1.

**Card Assembly**

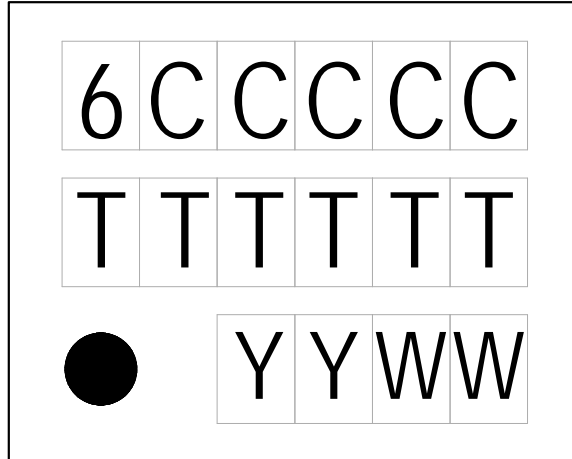
- A No-Clean, Type-3 solder paste is recommended.
- The recommended card reflow profile is per the JEDEC/IPC J-STD-020C specification for Small Body Components.

# Si516

## 8. Top Marking

Use the part number configuration utility located at: [www.silabs.com/VCXOPartNumber](http://www.silabs.com/VCXOPartNumber) to cross-reference the mark code to a specific device configuration.

### 8.1. Si516 Top Marking



### 8.2. Top Marking Explanation

<b>Mark Method:</b>	Laser	
<b>Line 1 Marking:</b>	6 = Si516 CCCCC = Mark Code	6CCCCC
<b>Line 2 Marking:</b>	TTTTTT = Assembly Manufacturing Code	TTTTTT
<b>Line 3 Marking:</b>	Pin 1 indicator.	Circle with 0.5 mm diameter; left-justified
	YY = Year. WW = Work week. Characters correspond to the year and work week of package assembly.	YYWW

## DOCUMENT CHANGE LIST

### Revision 0.9 to Revision 1.0

- Updated Table 1 on page 4.
  - Updates to supply current typical and maximum values for CMOS, LVDS, LVPECL and HCSL.
  - CMOS frequency test condition corrected to 100 MHz.
  - Updates to OE VIH minimum and VIL maximum values.
- Updated Table 3 on page 5.
  - Dual CMOS nominal frequency maximum added.
  - Disable time maximum values updated.
  - Enable time parameter added.
- Updated Table 4 on page 6.
  - CMOS output rise / fall time typical and maximum values updated.
  - LVPECL/HCSL output rise / fall time maximum value updated.
  - LVPECL output swing maximum value updated.
  - LVDS output common mode typical and maximum values updated.
  - HCSL output swing maximum value updated.
  - Duty cycle minimum and maximum values tightened to 48/52%.
- Updated Table 5 on page 7.
  - Phase jitter test condition, typical and maximum value updated.
  - Phase noise typical values updated.
  - Additive RMS jitter due to external power supply noise typical values updated.
- Added Tables 6, 7, 8 for LVDS, HCSL, CMOS and Dual CMOS operations.
- Added note to Figure 2 clarifying CMOS and Dual CMOS maximum frequency.
- Updated Figure 5 outline diagram to correct pinout.
- Updated “8. Top Marking” section and moved to page 20.



## ClockBuilder Pro

One-click access to Timing tools, documentation, software, source code libraries & more. Available for Windows and iOS (CBGo only).

[www.silabs.com/CBPro](http://www.silabs.com/CBPro)



**Timing Portfolio**  
[www.silabs.com/timing](http://www.silabs.com/timing)



**SW/HW**  
[www.silabs.com/CBPro](http://www.silabs.com/CBPro)



**Quality**  
[www.silabs.com/quality](http://www.silabs.com/quality)



**Support and Community**  
[community.silabs.com](http://community.silabs.com)

### Disclaimer

Silicon Laboratories intends to provide customers with the latest, accurate, and in-depth documentation of all peripherals and modules available for system and software implementers using or intending to use the Silicon Laboratories products. Characterization data, available modules and peripherals, memory sizes and memory addresses refer to each specific device, and "Typical" parameters provided can and do vary in different applications. Application examples described herein are for illustrative purposes only. Silicon Laboratories reserves the right to make changes without further notice and limitation to product information, specifications, and descriptions herein, and does not give warranties as to the accuracy or completeness of the included information. Silicon Laboratories shall have no liability for the consequences of use of the information supplied herein. This document does not imply or express copyright licenses granted hereunder to design or fabricate any integrated circuits. The products must not be used within any Life Support System without the specific written consent of Silicon Laboratories. A "Life Support System" is any product or system intended to support or sustain life and/or health, which, if it fails, can be reasonably expected to result in significant personal injury or death. Silicon Laboratories products are generally not intended for military applications. Silicon Laboratories products shall under no circumstances be used in weapons of mass destruction including (but not limited to) nuclear, biological or chemical weapons, or missiles capable of delivering such weapons.

### Trademark Information

Silicon Laboratories Inc., Silicon Laboratories, Silicon Labs, SiLabs and the Silicon Labs logo, CMEMS®, EFM, EFM32, EFR, Energy Micro, Energy Micro logo and combinations thereof, "the world's most energy friendly microcontrollers", Ember®, EZLink®, EZMac®, EZRadio®, EZRadioPRO®, DSPLL®, ISOmodem®, Precision32®, ProSLIC®, SiPHY®, USBXpress® and others are trademarks or registered trademarks of Silicon Laboratories Inc. ARM, CORTEX, Cortex-M3 and THUMB are trademarks or registered trademarks of ARM Holdings. Keil is a registered trademark of ARM Limited. All other products or brand names mentioned herein are trademarks of their respective holders.



Silicon Laboratories Inc.  
400 West Cesar Chavez  
Austin, TX 78701  
USA

<http://www.silabs.com>